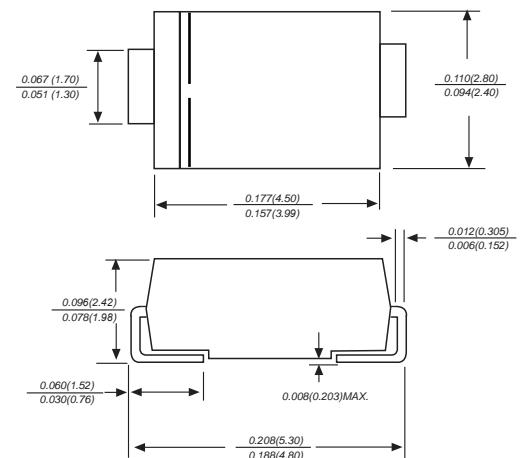


SURFACE MOUNT FAET RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed 250 °C/10 seconds at terminals

DO-214AC/SMA


Mechanical Data

Case : JEDEC DO-214AC/SMA Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.002 ounce, 0.07 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MDD FS2A	MDD FS2B	MDD FS2D	MDD FS2G	MDD FS2J	MDD FS2K	MDD FS2M	UNITS
Marking Code									
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at TL=110°C	I _(AV)					2.0			A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}					50.0			A
Maximum instantaneous forward voltage at 2.0A	V _F					1.30			V
Maximum DC reverse current TA=25°C at rated DC blocking voltage TA=100°C	I _R					5			uA
						50			
Typical junction capacitance (NOTE 1)	C _J					50.0			pF
Typical thermal resistance (NOTE 2)	R _{θJA}					15.0			°C/W
Maximum reverse recovery time (NOTE 3)	T _{rr}		150		250		500		ns
Operating junction and storage temperature range	T _{J,T_{STG}}					-65 to +150			°C

Note: 1.P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

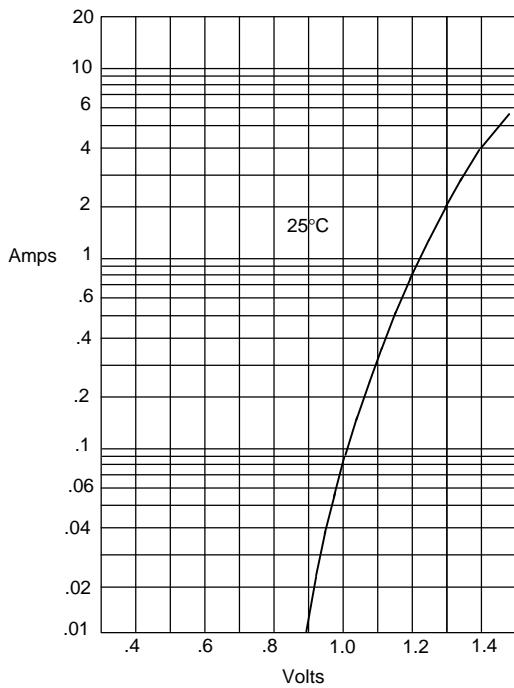
2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

3.Reverse recovery condition I_F=0.5A,I_R=1.0A,I_{rr}=0.25A

Ratings And Characteristic Curves

Figure 1

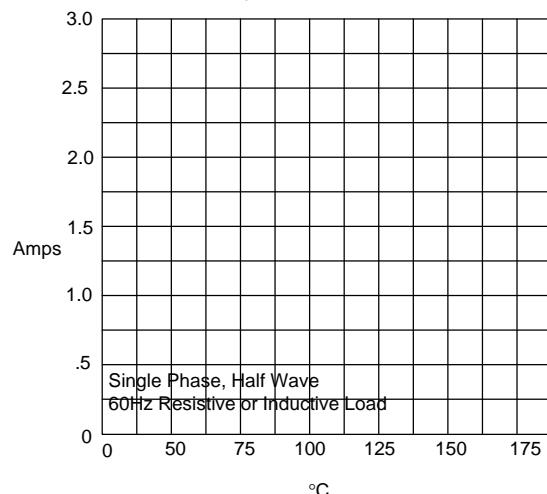
Typical Forward Characteristics



Instantaneous Forward Current - Amperesversus
Instantaneous Forward Voltage - Volts

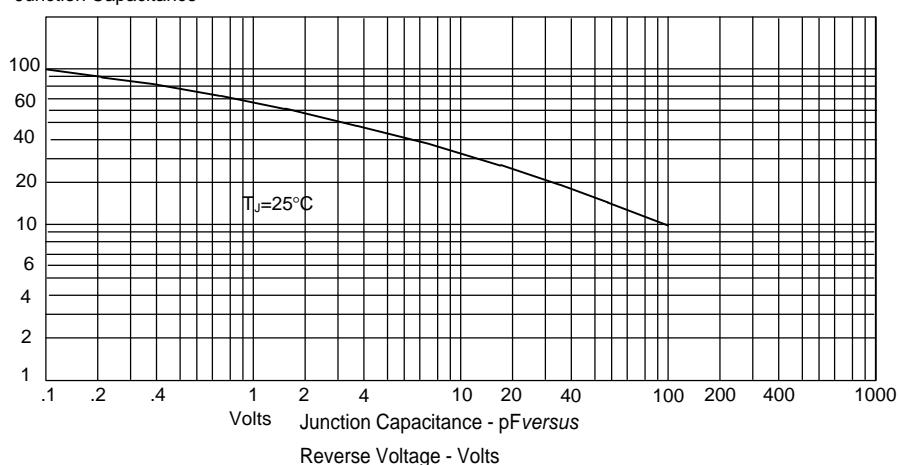
Figure 2

Forward Derating Curve



Average Forward Rectified Current - Amperesversus
Ambient Temperature - °C

Figure 3
Junction Capacitance



The curve above is for reference only.

Ratings And Characteristic Curves

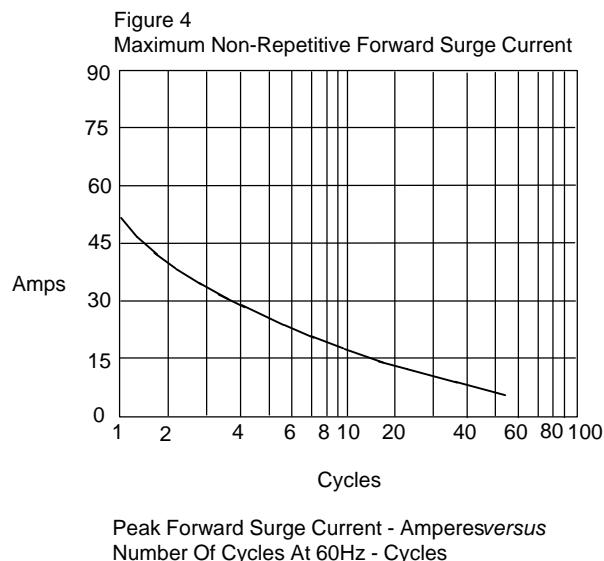
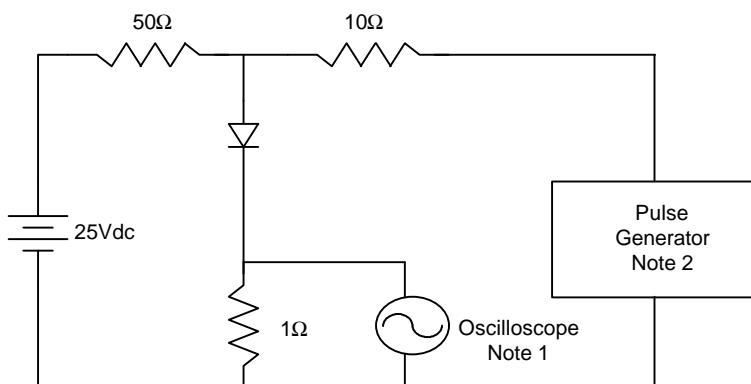
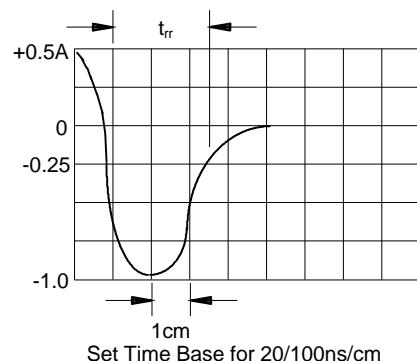


Figure 5
Reverse Recovery Time Characteristic And Test Circuit Diagram



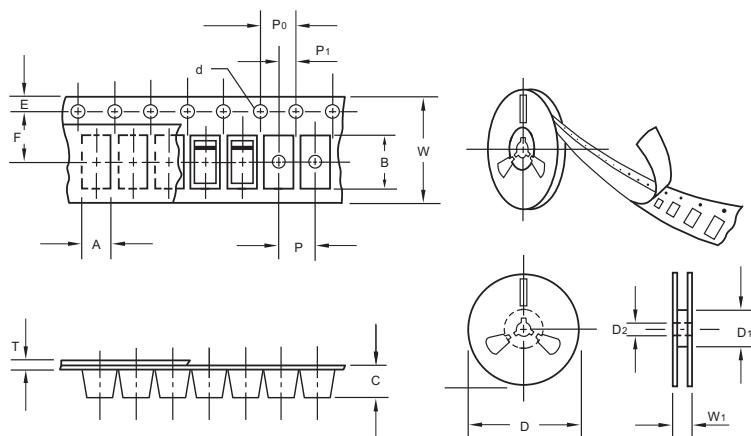
Notes:

1. Rise Time = 7ns max.
- Input impedance = 1 megohm, 22pF
2. Rise Time = 10ns max.
- Source impedance = 50 ohms
3. Resistors are non-inductive



The curve above is for reference only.

Packing information



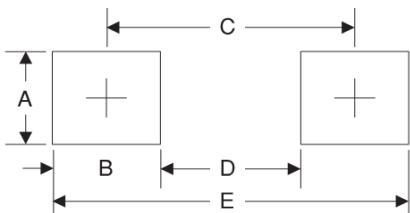
Item	Symbol	Tolerance	SMA
Carrier width	A	0.1	2.80
Carrier length	B	0.1	5.33
Carrier depth	C	0.1	2.36
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	62.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.28
Tape width	W	0.3	12.00
Reel width	W ₁	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMA	7"	2,000	4.0	4,000	183*155*183	178	382*356*392	80,000	16.0
SMA	11"	5,000	4.0	10,000	290*290*38	330	310*310*360	80,000	11.0
SMA	13"	7,500	4.0	15,000	335*335*38	330	350*330*360	120,000	14.5

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.93	0.154
D	2.41	0.095
E	5.45	0.215